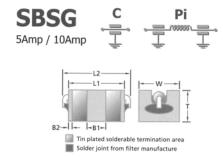


Surface Mount EMI Filters

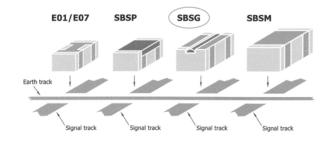


	С	Pi
L1	4.55 ± 0.25 (0.179 ± 0.010)	4.55 ± 0.25 (0.179 ± 0.010)
L2	4.70 ± 0.4 (0.185 ± 0.015)	5.25 ± 0.4 (0.207 ± 0.015)
W	3.20 ± 0.2 (0.126 ± 0.008)	3.20 ± 0.2 (0.126 ± 0.008)
Т	2.50 ± 0.15 (0.098 ± 0.006)	2.50 ± 0.15 (0.098 ± 0.006)
B1	1.50 ± 0.4 (0.059 ± 0.015)	1.50 ± 0.4 (0.059 ± 0.015)
B2	0.30 ± 0.25 (0.012 ± 0.010)	0.30 ± 0.25 (0.012 ± 0.010)

Earth pad overall min = 5.8 (0.228)	Earth track width = 1.5 (0.059")
Signal track width = 3.2 (0.126*)	
Coloured area to be solderable and free from	
varnish	Signal pad overall min = 8.0 (0.315)
	Pad spacing = 3.9 (0.153)

Recommended pad/track details

Ту	ре	SBSGC	SBSGP	
Chip	Size	1812	1812	
Max C	urrent	10A	5A	
Rated Voltage	Dielectric	Minimum and maximum capacitance values		
50Vdc	COG/NPO	-	-	
SOVAC	X7R	220nF	220nF	
100Vdc	COG/NPO	-	-	
Toovac	X7R	100nF-150nF	100nF-150nF	
200Vdc	COG/NPO	-	-	
200 v ac	X7R	68nF	68nF	
500Vdc	COG/NPO	-	-	
500000	X7R	1nF-47nF	1nF-47nF	

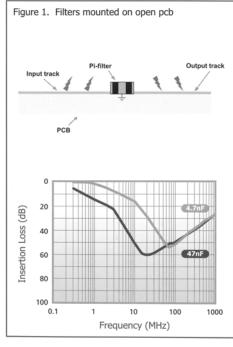


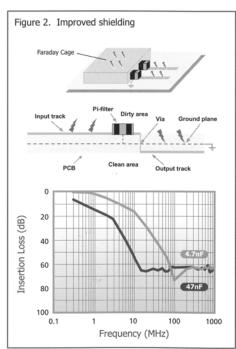
Effects of mounting method on insertion loss

C and Pi filters are mounted to PCBs and soldered in identical manner to chip capacitors. Solder connections made to each end (signal lines) and each side band (earth track).

Whilst SBSG, SBSM and SBSP filters can be mounted conventionally on PCBs, they are also suitable for mounting in a wall or partition on a board. This greatly improves the screening between filter input and output, thereby enhancing the high frequency response.

The following insertion loss curves (for SBSP, SBSG, SBSM Pi filters), based on actual measurements, show the effect. It can be seen that the filters conventionally mounted (Fig. 1) exhibit a drop in attenuation at higher frequencies. Improved shielding methods (Fig. 2), maintain excellent suppression characteristics to 1GHz and above. See below for application example.







Insertion loss tables for surface mount EMI filters - C filter

							Тур	ical No-Lo	ad Insert	ion Loss (dB)*
Product Code	Packing	Capacitance (±20%)	Dielectric	Rated Voltage (dc)	DWV (dc)	Approximate Resonant Frequency (MHz)	0.1MHz	1MHz	10MHz	100MHz	1GHz
SBSGC5000102MX		1.0nF	X7R	500	750	186	0	0	5	23	18
SBSGC5000152MX		1.5nF	X7R	500	750	147	0	0	8	27	18
SBSGC5000222MX	s) Is)	2.2nF	X7R	500	750	130	0	0	11	32	18
SBSGC5000332MX	reels) 'reels)	3.3nF	X7R	500	750	110	0	1	14	34	18
SBSGC5000472MX	7" 1	4.7nF	X7R	500	750	100	0	2	17	40	18
SBSGC5000682MX	ed / mr / m /	6.8nF	X7R	500	750	80	0	4	20	38	18
SBSGC5000103MX	k Packed (178mm (330mm	10nF	X7R	500	750	62.5	0	5	24	38	18
SBSGC5000153MX	Bulk Packed eel (178mm eel (330mm	15nF	X7R	500	750	50	0	8	27	38	18
SBSGC5000223MX	B = Bulk Packed -and-Reel (178mm and-Reel (330mm)	22nF	X7R	500	750	39	0	11	32	39	18
SBSGC5000333MX	B and-and	33nF	X7R	500	750	33	1	14	34	39	18
SBSGC5000473MX	Tape- Tape-	47nF	X7R	500	750	28	2	17	36	39	18
SBSGC2000683MX	= = D	68nF	X7R	200	500	23	3	20	37	39	18
SBSGC1000104MX	⊢ ~	100nF	X7R	100	250	19	5	23	41	39	18
SBSGC1000154MX		150nF	X7R	100	250	15.5	8	27	47	39	18
SBSGC0500224MX		220nF	X7R	050	125	13	11	30	49	39	18

^{* -} Insertion Loss performance quoted is measured on an open board mounted on a brass backplane in a 50Ω system. Performance curves can be supplied on request. Performance in circuit is liable to be different and is affected by board material, track layout, grounding efficiency and circuit impedances. Shielding can be used to improve high frequency performance.

Insertion loss tables for surface mount EMI filters - Pi filter

							Тур	ical No-Lo	ad Insert	ion Loss (dB)*
Product Code	Packing	Capacitance (±20%)	Dielectric	Rated Voltage (dc)	DWV (dc)	Approximate Resonant Frequency (MHz)	0.1MHz	1MHz	10MHz	100MHz	1GHz
SBSGP5000102MX		1.0nF	X7R	500	750	140	0	0	5	39	18
SBSGP5000152MX		1.5nF	X7R	500	750	100	0	0	8	41	18
SBSGP5000222MX	(5)	2.2nF	X7R	500	750	75	0	0	10	39	18
SBSGP5000332MX	reels) ′ reels)	3.3nF	X7R	500	750	54	0	1	15	39	18
SBSGP5000472MX	7" 1	4.7nF	X7R	500	750	44	0	2	17	39	18
SBSGP5000682MX	pa / mı / m	6.8nF	X7R	500	750	35	0	3	23	39	18
SBSGP5000103MX	Bulk Packed teel (178mm eel (330mm	10nF	X7R	500	750	28	0	5	28	39	18
SBSGP5000153MX	\sim \sim \sim	15nF	X7R	500	750	23	0	8	35	39	18
SBSGP5000223MX	B = Bull and-Reel and-Reel	22nF	X7R	500	750	19	0	10	43	39	18
SBSGP5000333MX	B -and	33nF	X7R	500	750	15	1	12	46	39	18
SBSGP5000473MX	ape.	47nF	X7R	500	750	12	2	14	53	39	18
SBSGP2000683MX	= = E = =	68nF	X7R	200	500	10	3	16	55	39	18
SBSGP1000104MX	⊢ ~	100nF	X7R	100	250	7.5	5	17	56	39	18
SBSGP1000154MX		150nF	X7R	100	250	6	8	20	58	39	18
SBSGP0500224MX		220nF	X7R	050	125	5.2	11	25	58	39	18

^{* -} Insertion Loss performance quoted is measured on an open FR4 board mounted on a brass backplane in a 50Ω system. Performance curves can be supplied on request. Performance in circuit is liable to be different and is affected by board material, track layout, grounding efficiency and circuit impedances. Shielding can be used to improve high frequency performance.

Ordering Information

SBS	G	Р	500	0473	M	Х	Т
Туре	Size	Configuration	Rated Voltage	Capacitance in Pico farads (pF)	Tolerance	Dielectric	Packaging
Surface mount board filter	G = 1812	C = C section P = Pi Section	050 = 50Vdc 100 = 100Vdc 200 = 200Vdc 500 = 500Vdc	First digit is 0. Second and third digits are significant figures of capacitance code. The fourth digit is number of zeros following. Example: 0473 = 47nF	M = ±20%	X = X7R	T=178mm (7") reel R=330mm (13") reel B = Bulk

Reeled Quantities

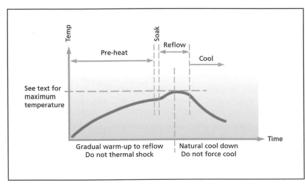
178mm (7") reel	1812	ۍ.
17611111 (7) Teel	500	٥.

330mm (13") reel	1812
330IIIII (13) Teel	2000

Surface mount and panel mount solder-in filters

Solder pad layouts are included with the detailed information for each part.

Recommended soldering profile



Soldering of filters

The soldering process should be controlled such that the filter does not experience any thermal shocks which may induce thermal cracks in the ceramic dielectric.

The pre-heat temperature rise of the filter should be kept to around 2°C per second. In practice successful temperature rises tend to be in the region of 1.5°C to 4°C per second dependent upon substrate and components.

The introduction of a soak after pre-heat can be useful as it allows temperature uniformity to be established across the substrate thus preventing substrate warping. The magnitude or direction of any warping may change on cooling imposing damaging stresses upon the filter.

E01, E03, E07 SBSP ranges are compatible with all standard solder types including lead-free, maximum temperature

260°C. For SBSG, SBSM and SFSS ranges, solder time should be minimised, and the temperature controlled to a maximum of 220°C. For SFSR, SFST and SFSU ranges the maximum temperature is 250°C.

Cooling to ambient temperature should be allowed to occur naturally. Natural cooling allows a gradual relaxation of thermal mismatch stresses in the solder joints. Draughts should be avoided. Forced air cooling can induce thermal breakage, and cleaning with cold fluids immediately after a soldering process may result in cracked filters.

Note: The use of FlexiCap™ terminations is strongly recommended to reduce the risk of mechanical cracking.

Soldering to axial wire leads

Soldering temperature

The tip temperature of the iron should not exceed 300°C.

Dwell time

Dwell time should be 3-5 seconds maximum to minimise the risk of cracking the capacitor due to thermal shock.

Heat sink

Where possible, a heat sink should be used between the solder joint and the body, especially if longer dwell times are required.

Bending or cropping of wire leads

Bending or cropping of the filter terminations should not be carried out within 4mm (0.157") of the epoxy encapsulation, the wire should be supported when cropping.

A more comprehensive application note covering installation of all Syfer products is available on the Syfer website.

Mouser Electronics

Authorized Distributor

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Knowles:

SBSGP5000223MXT	SBSGP0500224MXT	SBSGP5000473MXT	SBSGP5000103MXT	SBSGP1000154MXT
SBSGP2000683MXT	SBSGP5000153MXT	SBSGP5000222MXT	SBSGP5000102MXT	SBSGP1000104MXT
SBSGP5000472MXT	SBSGP0500224MXB	SBSGP1000104MXB	SBSGP1000154MXB	SBSGP5000223MXB
SBSGP5000332MXT	SBSGP5000682MXT	SBSGP5000222MXB	SBSGP2000683MXB	SBSGC5000102MXB
SBSGC1000104MXB	SBSGP5000103MXB	SBSGP5000472MXB	SBSGP5000102MXB	SBSGP5000682MXB
SBSGP5000473MXB	SBSGC5000473MXB	SBSGC0500224MXB	SBSGC5000473MXT	SBSGC0500224MXT
SBSGC1000154MXT	SBSGC5000223MXB	SBSGP5000153MXB	SBSPP1000103MXB	SBSGC1000154MXB
SBSGC5000223MXT	SBSGP5000332MXB	SBSGC5000103MXB	SBSGC5000103MXT	SBSGC5000472MXB
SBSGC5000152MXB	SBSGC5000152MXT	SBSGC2000683MXB	SBSGC5000102MXT	SBSGC5000153MXT
SBSGP5000103MXR	SBSGP5000473MXR	SBSGC0500224MXR	SBSGC1000104MXR	SBSGC1000104MXT
SBSGC1000154MXR	SBSGC2000683MXR	SBSGC2000683MXT	SBSGC5000102MXR	SBSGC5000103MXR
SBSGC5000152MXR	SBSGC5000153MXB	SBSGC5000153MXR	SBSGC5000222MXB	SBSGC5000222MXR
SBSGC5000222MXT	SBSGC5000223MXR	SBSGC5000332MXB	SBSGC5000332MXR	SBSGC5000332MXT
SBSGC5000333MXB	SBSGC5000333MXR	SBSGC5000333MXT	SBSGC5000472MXR	SBSGC5000472MXT
SBSGC5000473MXR	SBSGC5000682MXB	SBSGC5000682MXR	SBSGC5000682MXT	SBSGP0500224MXR
SBSGP1000104MXR	SBSGP1000154MXR	SBSGP2000683MXR	SBSGP5000102MXR	SBSGP5000152MXB
SBSGP5000152MXR	SBSGP5000152MXT	SBSGP5000153MXR	SBSGP5000222MXR	SBSGP5000223MXR
SBSGP5000332MXR	SBSGP5000333MXB	SBSGP5000333MXR	SBSGP5000333MXT	SBSGP5000472MXR
SBSGP5000682MXR				